

FUTURE UDIMM DDR5

Introduction

HIKSEMI memory module FUTURE UDIMM is a DDR5 memory module, which is made of high-quality DRAM chips and mature production technology, which makes it more compatible, stable and cost-effective. Can be widely used in PC installations, various high-bandwidth, high-performance system applications.



Features

Cost-effective

Adopt selected IC to make the system run stably and perform better.

Good compatibility

Better compatibility, compatible with more products after HIKSEMI optimization.

Ordering Information

Frequency	Capacity	Model
6000MHz	16GB×2	HSC532U60C3
	32GB×2	HSC564U60C3
6400MHz	16GB×2	HSC532U64C3
	32GB×2	HSC564U64C3
6800MHz	16GB×2	HSC532U68C3
	32GB×2	HSC564U68C3
7200MHz	16GB×2	HSC532U72C3
	32GB×2	HSC564U72C3
7600MHz	16GB×2	HSC532U76C3
	32GB×2	HSC564U76C3
8000MHz	16GB×2	HSC532U80C3
	32GB×2	HSC564U80C3



Please contact the local sales for detailed model information.





Specification

Name	FUTURE UDIMM DDR5		
Capacity	16GB×2	32GB×2	
Interface	DDR5		
frequency	6000/6400/6800/7200/7600/8000MHz		
Overclock model	XMP/EXPO		
Pin	288pin		
PCB Size(L×W×H mm)	133.25*31.25*3.77		
Operation temperature	0 °C to 85 °C (32 °F to 185 °F)		
Limited warranty period	Lifetime warranty		
Weight	70g×2		

Revision History

Version	Description	Date
V1.0.0	FUTURE UDIMM DDR5	20240410

Data subject to change without notice.

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The Manual includes instructions for using and managing the Product. Pictures, charts, images and all other information hereinafter are for description and explanation only. The information contained in the Manual is subject to change, without notice, due to firmware updates or other reasons. Please find the latest version of this Manual at the HIKSTORAGE website (www.hiksemitech.com).

